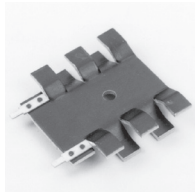


BOARD LEVEL POWER SEMICONDUCTOR HEAT SINKS



288 SERIES

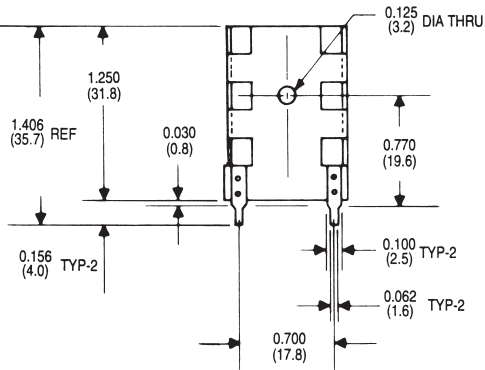
COMPACT WAVE-SOLDERABLE LOW-COST
HEAT SINKS

TO-220 and TO-202

Mounting tabs are pre-tinned to ensure excellent wave-solder bond and good electrical connections for vertical mounting of TO-220 and TO-202 semiconductor packages. These heat sinks are designed for use where minimum PC board space is available. The 288-1AB is a stamped aluminum heat sink, black anodized, designed for applications requiring good heat dissipation from a heat sink occupying minimum space, available at minimum cost.

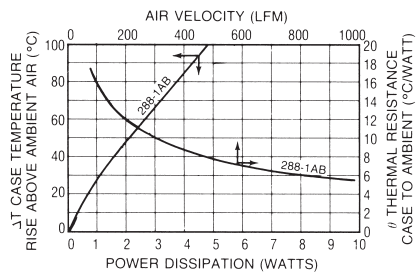
Standard P/N	Height Above PC Board in. (mm)	Maximum Footprint in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
288-1ABE	1.250 (31.8)	0.875 (22.2) x 0.215 (5.5)	85°C @ 4W	12°C/W @ 200 LFM	0.0057 (2.59)

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED
CONVECTION CHARACTERISTICS



TOP-MOUNT BOOSTER HEAT SINKS FOR USE WITH
270/272/280 SERIES

271 SERIES

This top-hat style booster heat sink can be added to any of the 270, 272, or 280 Series for improved performance. NOTE A: Thermal resistance with one 271-AB. NOTE B: Thermal resistance (total) as shown with (2) 271-AB types added to (1) 272-AB type.

Standard P/N	Height Above Semiconductor Case in. (mm)	Horizontal Mounting Footprint Dimensions in. (mm)	Thermal Performance at Typical Load		Weight lbs. (grams)
			Natural Convection	Forced Convection	
271-AB	0.500 (12.7)	1.750 (44.5) x 0.700 (17.8)	62°C @ 4W (NOTE A) 31 °C @ 4W (NOTE B)	5.1°C/W @ 400 LFM 1.8°C/W 400 LFM (NOTE B)	0.0052 (2.36)

Material: Aluminum, Black Anodized

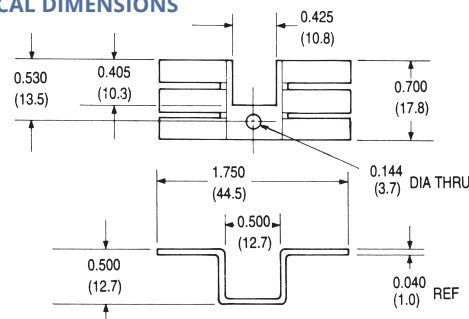


TOP-MOUNT BOOSTER HEAT SINKS FOR USE WITH
270/272/280 SERIES

271 SERIES

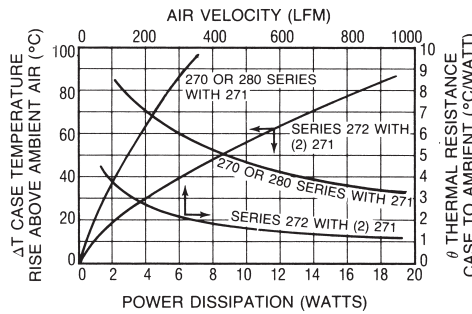
TO-220

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED
CONVECTION CHARACTERISTICS



270, 272, &
280 SERIES

SMALL FOOTPRINT LOW-COST HEAT SINKS

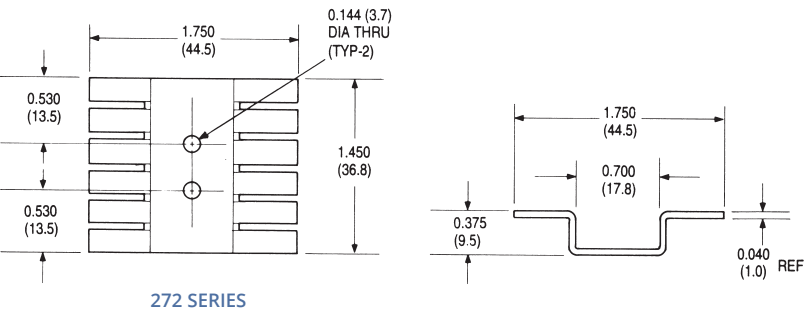
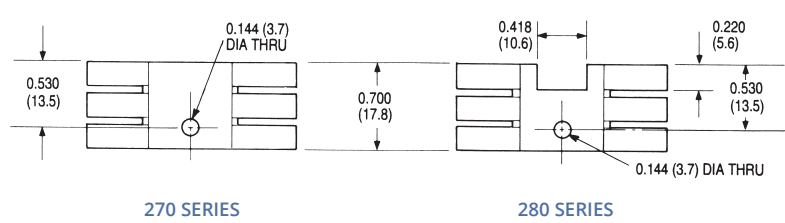
TO-220 and TO-202

These exceptionally low-cost heat sinks can be mounted horizontally under a TO-220 or TO-202 case style with a maximum height of only 0.375 in. (9.4). For added performance, a 271 Series heat sink can also be used for double-sided heat dissipation. The 270-AB and 280-AB accept one power semiconductor; the 272-AB is designed for two power semiconductors. Specify solderable tab options for the **272 Series** by the addition of suffix "O1" or "O2" to the standard part number (i.e. 272-AB01 or 272-AB02).

Standard P/N	Height Above PC Board in. (mm)	Horizontal Mounting Maximum Footing in. (mm)	Solderable Tab Options	Thermal Performance at Typical Load		Weight lbs. (grams)
				Natural Convection	Forced Convection	
270-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0052 (2.36)
272-AB	0.375 (9.4)	1.750 (44.5) x 1.450 (36.8)	01,02	42°C @ 4W	3.6°C/W @ 400 LFM	0.0105 (5.72)
280-AB	0.375 (9.4)	1.750 (44.5) x 0.700 (17.8)	—	70°C @ 4W	6.0°C/W @ 400 LFM	0.0048 (2.18)

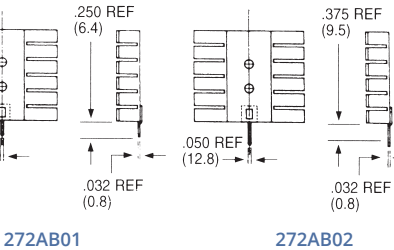
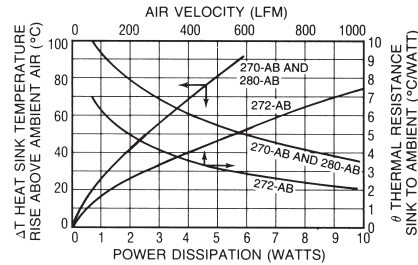
Material: Aluminum, Black Anodized

MECHANICAL DIMENSIONS



Dimensions: in. (mm)

NATURAL AND FORCED
CONVECTION CHARACTERISTICS



Note:
1. Suggested Tab Hole = 0.075 ±0.003 plated with 0.100 pad